



SOT865-3

plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; 0.65 mm pitch, 7 mm x 7 mm x 0.85 mm body

3 June 2019

Package information

1 Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | HVQFN32 |
| Package type industry code | HVQFN32 |
| Package style descriptive code | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MO-220 |
| Mounting method type | S (surface mount) |
| Issue date | 05-02-2009 |
| Manufacturer package code | SOT865-3 |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-----|------|-----|------|
| package length | 6.9 | 7 | 7.1 | mm |
| package width | 6.9 | 7 | 7.1 | mm |
| seated height | 0.8 | 0.85 | 1 | mm |
| nominal pitch | - | 0.65 | - | mm |
| actual quantity of termination | - | 32 | - | |



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2 Package outline

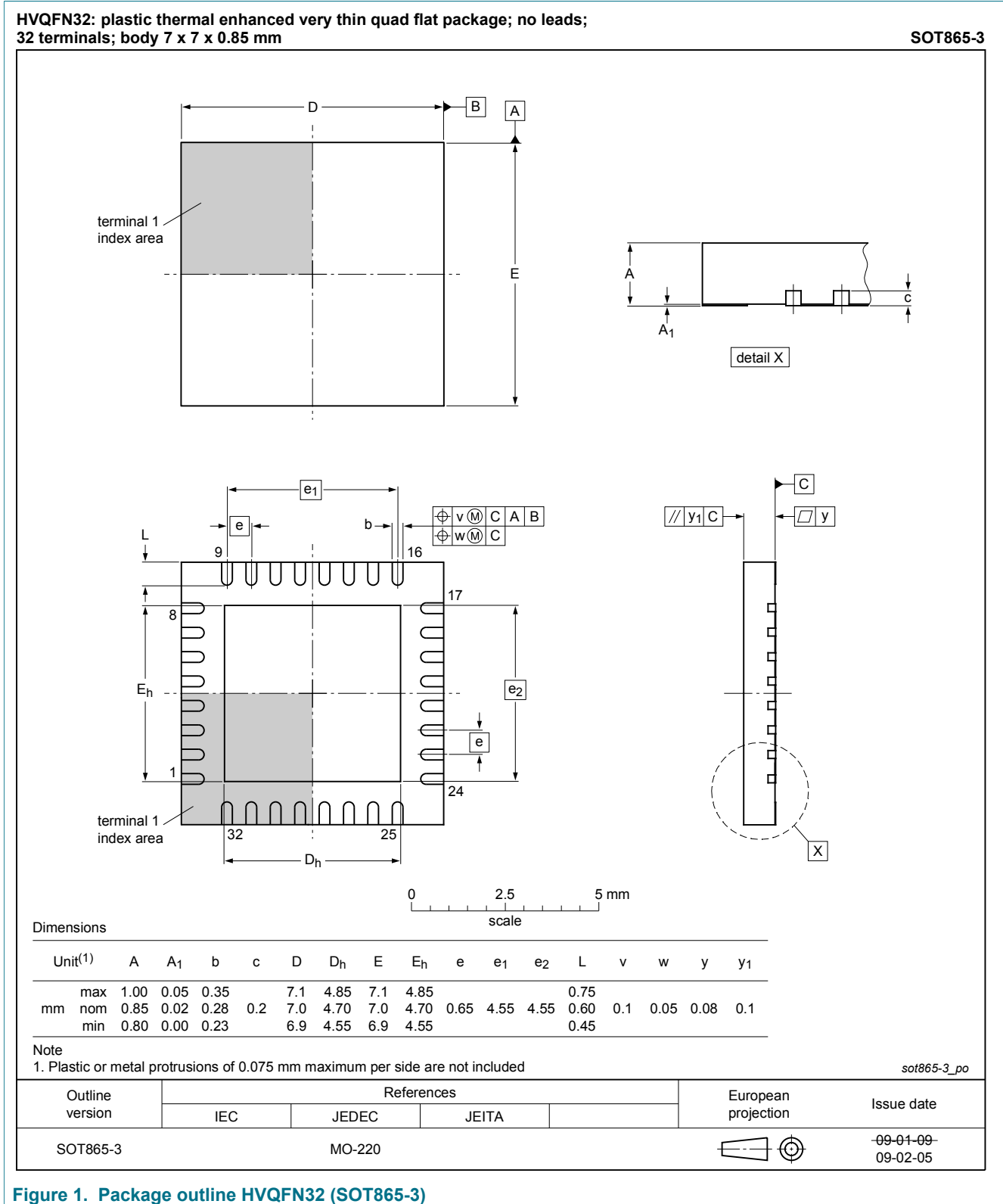


Figure 1. Package outline HVQFN32 (SOT865-3)

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3 Soldering

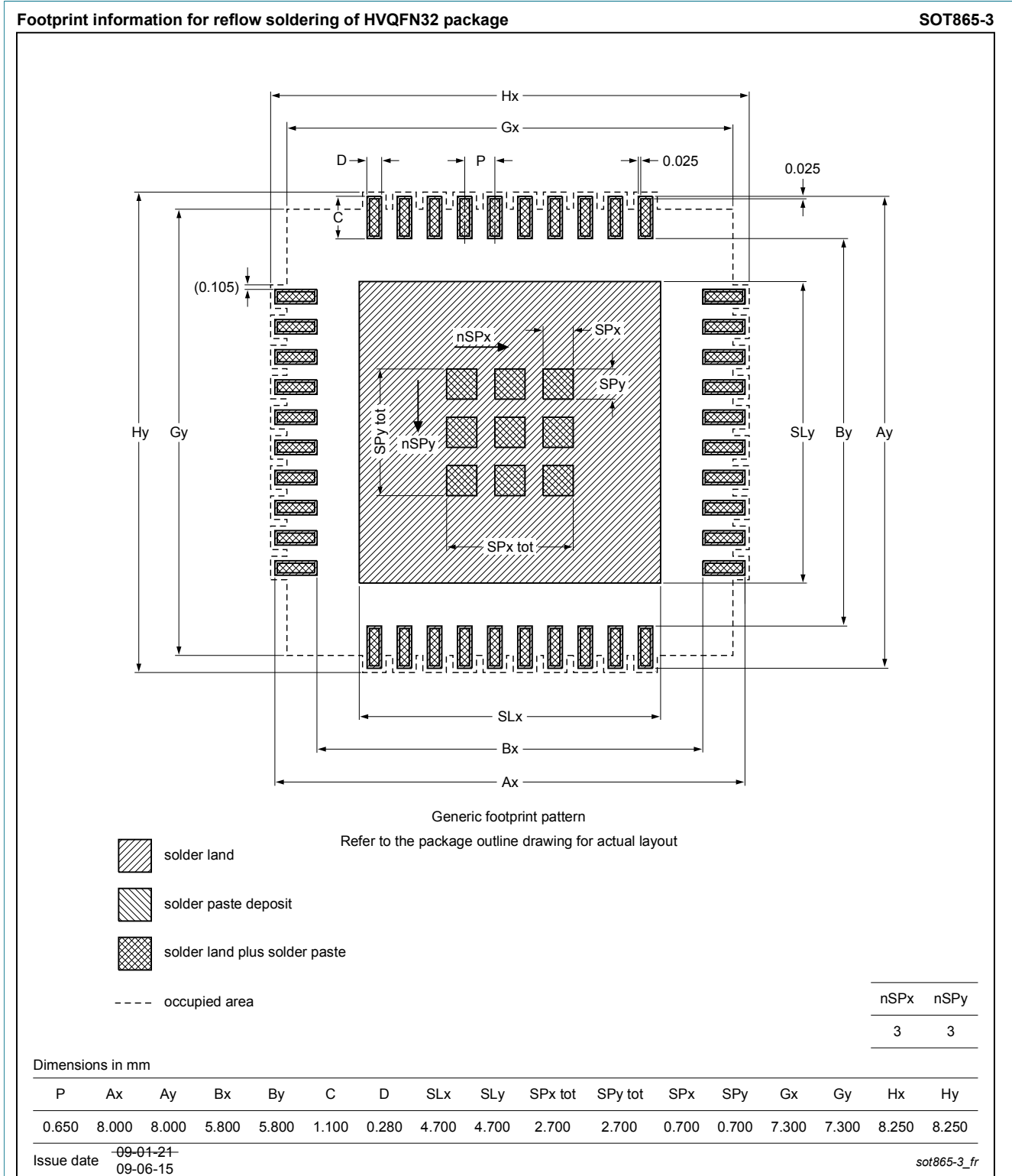


Figure 2. Reflow soldering footprint for HVQFN32 (SOT865-3)

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4 Legal information

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